PCN Number: 20190923001				PCN Date: Sept. 27, 2019					
Title: Datasheet fo									
Customer Contact:	PCN Mana	ger			D	Dept:		Quality Services	
Change Type:		<u> </u>							
Assembly Site			Design				Wafe	er Bump Site	
Assembly Process			Data Sheet					er Bump Material	
Assembly Materials			Part number change			Wafer Bump Process			
Mechanical Specification			Test Site				Wafer Fab Site		
Packing/Shipping/Labeling			Test Process				Wafer Fab Materials		
						er Fab Process			
Notification Details									
Description of Chang	je:								
Texas Instruments Inc The product datasheet The following change h	(s) is being	updat	ed as sumi	marized below				TPA6211A1-Q1	
 INSTRUMENTS 					SBO	S55	5E-JUN	E 2011-REVISED AUGUST 2019	
Changes from Revision D	(August 2019)	to Revis	sion E					Page	
Changed packaging to H	VSSOP							1	
								25	
Changes from Revision C	(August 2016)	to Revis	sion D					Page	
Deleted AEC-Q100 from the Feature: Qualified for automotive applications								1	
Deleted Feature: Tempe	Deleted Feature: Temperature Grade 2								
Changed the ESD Ratings table									
The datasheet number Device Family	will be cha	nging.	Change F	rom:			Chan	ge To:	
							Chan	ge 10.	
TPA6211A1-Q1			SBOS555	BOS555C SBOS			OS555E		
These changes may be	reviewed a	t the	datasheet l	inks provided	d.				
http://www.ti.com/pro									
Reason for Change:									
To accurately reflect de	evice charac	tericti	ics						
				ality as Dali	- h !!	14-			
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative): No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.									
Changes to product identification resulting from this PCN:									
changes to product	achthicat	None.							
	lacinente								

For questions regarding this notice, e-mails can be sent to the contacts shown below or your local Field Sales Representative.

Location	E-Mail
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